

wherein the active coating layer is removable from the substrate, and wherein the active coating material is applied electrostatically as a powder.

38. A method according to claim 37, which further includes the step of removing the active coating layer from the substrate.

39. A method according to claim 37, wherein the substrate is pre-coated with one or more coating layers removable from the substrate and the active coating layer is removable therewith.

40. A method according to claim 37, which further includes the step of applying a cover coating material onto the active coating layer to form a cover coating layer such that the active coating layer is substantially completely covered by the cover coating layer, and such that the cover coating layer is removable from the substrate.

41. A method according to claim 40, wherein the cover coating material is applied electrostatically as a powder and after application is fused to form a cover film coating.

42. A method according to claim 40, wherein the cover coating layer is removable with the active coating layer.

43. A method according to claim 40, wherein the cover material includes biologically active material.

44. A method according to claim 40, wherein the method further includes the step of applying a further coating material to a surface of the substrate to form a further coating layer such that the further coating layer is removable from the substrate.

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45. A method according to claim 44, wherein the further coating material includes biologically active material, the further coating layer forming a further active coating layer and the method further includes the step of applying a further cover coating material onto the further active coating layer to form a further cover coating layer such that the further active coating layer is substantially completely covered by the further cover coating layer and such that the further cover coating layer is removable from the substrate.

46. A method according to claim 45, wherein the active material of the active coating layer and the further active coating layer are the same.

47. A method according to claim 40, wherein the method includes the step of applying a second active coating layer onto a surface of the substrate, the

second active coating layer forming a second active coating region on the surface of the substrate, the second active coating layer being removable from the substrate, and applying a second cover coating layer onto the second active coating layer to form a second cover coating layer such that the second active coating layer is substantially completely covered by the second cover coating layer, the second cover coating layer being substantially separate from the first cover coating layer, and being removable from the substrate.

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48. A method according to claim 37 which comprises applying to the substrate a base coating layer, applying the active material to the base layer and applying a cover coating layer over the active coating layer, the three layers being removable together by peeling from the substrate in the form of a three-layer wafer.

49. A method according to claim 48, wherein the base coating layer and the cover coating layer are each applied electrostatically as a powder and each fused to form a film.

50. A method according to claim 37 wherein at least 90% by weight of the particles of the active coating material have a particle size in the range of from 1 to 45 microns.

51. A method according to claim 37 wherein 90% by weight of the particles have a size less than 70 microns, 50% by weight have a size less than 40 microns and 10% by weight have a size less than 10 microns.

52. A method according to claim 37 wherein the method comprises supporting the substrate adjacent to the source of the active coating material with a surface of the substrate maintained at such a different electric potential from that of the active coating material that the application of the electric potential causes the active coating material to move from the source of the active coating material towards the substrate, a surface of the substrate becoming coated with the active coating material.

53. A method according to claim 37 wherein the substrate is supported from above and the powder moves from the source upwards towards a lower surface of the substrate.

54. A method according to claim 37 wherein the quantity of active material in the active coating applied to the substrate is substantially equal to one dose of the active material.

55. A method according to claim 37 wherein the active coating material is applied to a plurality of individual regions on the surface of the substrate.

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56. A method of coating a substrate, the method comprising the steps of applying an active coating material to the substrate to form an active coating layer, the active coating material comprising biologically active material, wherein the active coating layer is removable from the substrate, and wherein the active coating material is applied electrostatically as a powder and after the active coating layer is applied the active coating material is fused to form an active film coating on the surface of the substrate.

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57. A method according to claim 56, which further includes the step of removing the active coating layer from the substrate.

58. A method according to claim 56, wherein the substrate is pre-coated with one or more coating layers removable from the substrate and the active coating layer is removable therewith.

59. A method according to claim 56, which further includes the step of applying a cover coating material onto the active coating layer to form a cover coating layer such that the active coating layer is substantially completely covered by the cover coating layer, and such that that cover coating layer is removable from the substrate.

60. A method according to claim 59, wherein the cover coating material is applied electrostatically as a powder and after application is fused to form a cover film coating.

61. A method according to claim 59, wherein the cover coating layer is removable with the active coating layer.

62. A method according to claim 59, wherein the cover material includes biologically active material.

63. A method according to claim 59, wherein the method further includes the step of applying a further coating material to a surface of the substrate to form a further coating layer such that the further coating layer is removable from the substrate.

64. A method according to claim 63, wherein the further coating material includes biologically active material, the further coating layer forming a further active coating layer and the method further includes the step of applying a further cover coating material onto the further active coating layer to form a further cover coating layer such that the further active coating layer is substantially completely covered by the further cover coating layer and such that the further cover coating layer is removable from the substrate.

65. A method according to claim 64, wherein the active material of the active coating layer and the further active coating layer are the same.

66. A method according to claim 59, wherein the method includes the step of applying a second active coating layer onto a surface of the substrate, the second active coating layer forming a second active coating region on the surface of the substrate, the second active coating layer being removable from the substrate, and applying a second cover coating layer onto the second active coating layer to form a second cover coating layer such that the second active coating layer is substantially completely covered by the second cover coating layer, the second cover coating layer being substantially separate from the first cover coating layer, and being removable from the substrate.

67. A method according to claim 56, which comprises applying to the substrate a base coating layer, applying the active material to the base layer and applying a cover coating layer over the active coating layer, the three layers being removable together by peeling from the substrate in the form of a three-layer wafer.

68. A method according to claim 67, wherein the base coating layer and the cover coating layer are each applied electrostatically as a powder and each

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fused to form a film.

69. A method according to claim 56, wherein at least 90% by weight of the particles of the active coating material have a particle size in the range of from 1 to 45 microns.

70. A method according to claim 56, wherein 90% by weight of the particles have a size less than 70 microns, 50% by weight have a size less than 40 microns and 10% by weight have a size less than 10 microns.

71. A method according to claim 56, wherein the method comprises supporting the substrate adjacent to source of the active coating material with a surface of the substrate maintained at such a different electric potential from that of the active coating material that the application of the electric potential causes the active coating material to move from the source of the active coating material towards the substrate, a surface of the substrate becoming coated with the active coating material.

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72. A method according to claim 56, wherein the substrate is supported from above and the powder moves from the source upwards towards a lower surface of the substrate.

73. A method according to claim 56, wherein the quantity of active material in the active coating applied to the substrate is substantially equal to one dose of the active material.

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74. A method according to claim 56, wherein the active coating material is applied to a plurality of individual regions on the surface of the substrate.

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75. A method of coating a substrate, the method comprising the steps of applying an active coating material to the substrate to form an active coating layer, the active coating material comprising biologically active material, wherein the active coating layer is removable from the substrate to form a solid dosage form, and the active coating material is applied electrostatically as a powder.

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76. A method according to claim 75, which further includes the step of removing the active coating layer from the substrate.

77. A method according to claim 75, wherein the substrate is pre-coated with one or more coating layers removable from the substrate and the active coating layer is removable therewith.

78. A method according to claim 75, which further includes the step of applying a cover coating material onto the active coating layer to form a cover

coating layer such that the active coating layer is substantially completely covered by the cover coating layer, and such that that cover coating layer is removable from the substrate.

79. A method according to claim 78, wherein the cover coating material is applied electrostatically as a powder and after application is fused to form a cover film coating.

80. A method according to claim 78, wherein the cover coating layer is removable with the active coating layer.

81. A method according to claim 78, wherein the cover material includes biologically active material.

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82. A method according to claim 78, wherein the method further includes the step of applying a further coating material to a surface of the substrate to form a further coating layer such that the further coating layer is removable from the substrate.

83. A method according to claim 82, wherein the further coating material includes biologically active material, the further coating layer forming a further active coating layer and the method further includes the step of applying a further

cover coating material onto the further active coating layer to form a further cover coating layer such that the further active coating layer is substantially completely covered by the further cover coating layer and such that the further cover coating layer is removable from the substrate.

84. A method according to claim 83, wherein the active material of the active coating layer and the further active coating layer are the same.

85. A method according to claim 78, wherein the method includes the step of applying a second active coating layer onto a surface of the substrate, the second active coating layer forming a second active coating region on the surface of the substrate, the second active coating layer being removable from the substrate, and applying a second cover coating layer onto the second active coating layer to form a second cover coating layer such that the second active coating layer is substantially completely covered by the second cover coating layer, the second cover coating layer being substantially separate from the first cover coating layer, and being removable from the substrate.

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86. A method according to claim 75, which comprises applying to the substrate a base coating layer, applying the active material to the base layer and applying a cover coating layer over the active coating layer, the three layers being removable together by peeling from the substrate in the form of a three-layer

wafer.

87. A method according to claim 86, wherein the base coating layer and the cover coating layer are each applied electrostatically as a powder and each fused to form a film.

88. A method according to claim 75, wherein at least 90% by weight of the particles of the active coating material have a particle size in the range of from 1 to 45 microns.

89. A method according to claim 75, wherein 90% by weight of the particles have a size less than 70 microns, 50% by weight have a size less than 40 microns and 10% by weight have a size less than 10 microns.

90. A method according to claim 75, wherein the method comprises supporting the substrate adjacent to source of the active coating material with a surface of the substrate maintained at such a different electric potential from that of the active coating material that the application of the electric potential causes the active coating material to move from the source of the active coating material towards the substrate, a surface of the substrate becoming coated with the active coating material.

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91. A method according to claim 75, wherein the substrate is supported from above and the powder moves from the source upwards towards a lower surface of the substrate.

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92. A method according to claim 75, wherein the active coating material is applied to a plurality of individual regions on the surface of the substrate.

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93. A method of coating a substrate, the method comprising the steps of applying an active coating material to the substrate to form an active coating layer, the active coating material comprising biologically active material, wherein the active coating layer is removable from the substrate to form a solid dosage form, and the active coating material is applied electrostatically as a powder, and wherein after the active coating layer is applied the active coating material is fused to form an active film coating on the surface of the substrate.

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94. A method according to claim 93, which further includes the step of applying a cover coating material onto the active coating layer to form a cover coating layer such that the active coating layer is substantially completely covered by the cover coating layer, and such that that cover coating layer is removable from the substrate, wherein the cover coating material is applied electrostatically as a powder and after application is fused to form a cover film coating.

95. A method according to claim 93, wherein at least 90% by weight of the particles of the active coating material have a particle size in the range of from 1 to 45 microns.

96. A method according to claim 93, wherein 90% by weight of the particles have a size less than 70 microns, 50% by weight have a size less than 40 microns and 10% by weight have a size less than 10 microns.

97. A method according to claim 93 wherein the active coating material is applied to a plurality of individual regions on the surface of the substrate.

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98. A method of coating a substrate, the method including the steps of applying an active coating material to the substrate to form an active coating layer, the active coating material comprising biologically active material, wherein the active coating layer is removable from the substrate, and wherein the active material is applied to a surface of the coating apparatus and the active coating is removed as a wafer.

99. A method according to claim 98 wherein the active material is applied to a conveyor belt.

100. A method according to claim 98, wherein the substrate is pre-coated with one or more coating layers removable from the substrate and the active coating layer is removable therewith.

101. A method according to claim 98, which further includes the step of applying a cover coating material onto the active coating layer to form a cover coating layer such that the active coating layer is substantially completely covered by the cover coating layer, and such that that cover coating layer is removable from the substrate.

102. A method according to claim 101, wherein the cover coating material is applied electrostatically as a powder and after application is fused to form a cover film coating.

103. A method according to claim 101, wherein the cover coating layer is removable with the active coating layer.

104. A method according to claim 101, wherein the cover material includes biologically active material

105. A method according to claim 101, wherein the method further includes the step of applying a further coating material to a surface of the

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substrate to form a further coating layer such that the further coating layer is removable from the substrate.

106. A method according to claim 105, wherein the further coating material includes biologically active material, the further coating layer forming a further active coating layer and the method further includes the step of applying a further cover coating material onto the further active coating layer to form a further cover coating layer such that the further active coating layer is substantially completely covered by the further cover coating layer and such that the further cover coating layer is removable from the substrate.

107. A method according to claim 106, wherein the active material of the active coating layer and the further active coating layer are the same.

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108. A method according to claim 101, wherein the method includes the step of applying a second active coating layer onto a surface of the substrate, the second active coating layer forming a second active coating region on the surface of the substrate, the second active coating layer being removable from the substrate, and applying a second cover coating layer onto the second active coating layer to form a second cover coating layer such that the second active coating layer is substantially completely covered by the second cover coating layer, the second cover coating layer being substantially separate from the first

cover coating layer, and being removable from the substrate.

109. A method according to claim 98, which comprises applying to the substrate a base coating layer, applying the active material to the base layer and applying a cover coating layer over the active coating layer, the three layers being removable together by peeling from the substrate in the form of a three-layer wafer.

110. A method according to claim 109, wherein the base coating layer and the cover coating layer are each applied electrostatically as a powder and each fused to form a film.

111. A method according to claim 98, wherein the method comprises supporting the substrate adjacent to source of the active coating material with a surface of the substrate maintained at such a different electric potential from that of the active coating material that the application of the electric potential causes the active coating material to move from the source of the active coating material towards the substrate, a surface of the substrate becoming coated with the active coating material.

112. A method according to claim 98, wherein the substrate is supported from above and the powder moves from the source upwards towards a lower

surface of the substrate.

113. A method according to claim 98, wherein the quantity of active material in the active coating applied to the substrate is substantially equal to one dose of the active material.

114. A method according to claim 98, wherein the wafer removed from the coated substrate is a solid dosage form.

115. A method according to claim 98, wherein the active coating material is applied to a plurality of individual regions on the surface of the substrate.

116. A method according to claim 98 wherein the active coating material is applied as a liquid and after the active coating layer is applied the active coating material is treated to form an active film coating.

117. A method according to claim 116, wherein a predetermined number of droplets of active coating material are applied to the surface of the substrate.

118. A method according to claim 116, wherein an ink jet head is used to apply coating material to the substrate.

119. A method according to claim 116, wherein the active coating material is applied in the form of individual liquid droplets of liquid directly towards a surface of the substrate.

120. A method of coating a substrate, the method comprising the steps of applying an active coating material to the substrate to form an active coating layer, the active coating material comprising biologically active material, wherein the active coating layer is removable from the substrate, and the active coating material is applied electrostatically as a powder, and wherein the active material is applied to a surface of the coating apparatus and the active coating is removed as a wafer.

121. A method according to claim 120, wherein the active material is applied to a conveyor belt.

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122. A method according to claim 120, wherein the substrate is pre-coated with one or more coating layers removable from the substrate and the active coating layer is removable therewith.

123. A method according to claim 120, which further includes the step of applying a cover coating material onto the active coating layer to form a cover coating layer such that the active coating layer is substantially completely

covered by the cover coating layer, and such that that cover coating layer is removable from the substrate, wherein the cover coating material is applied electrostatically as a powder and after application is fused to form a cover film coating.

124. A method according to claim 123, wherein the cover coating layer is removable with the active coating layer.

125. A method according to claim 123, wherein the cover material includes biologically active material

126. A method according to claim 123, wherein the method further includes the step of applying a further coating material to a surface of the substrate to form a further coating layer such that the further coating layer is removable from the substrate.

127. A method according to claim 126, wherein the method includes the step of applying a second active coating layer onto a surface of the substrate, the second active coating layer forming a second active coating region on the surface of the substrate, the second active coating layer being removable from the substrate, and applying a second cover coating layer onto the second active coating layer to form a second cover coating layer such that the second active

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coating layer is substantially completely covered by the second cover coating layer, the second cover coating layer being substantially separate from the first cover coating layer, and being removable from the substrate.

128. A method according to claim 120, which comprises applying to the substrate a base coating layer, applying the active material to the base layer and applying a cover coating layer over the active coating layer, the three layers being removable together by peeling from the substrate in the form of a three-layer wafer.

129. A method according to claim 128, wherein the base coating layer and the cover coating layer are each applied electrostatically as a powder and each fused to form a film.

130. A method according to claim 120, wherein at least 90% by weight of the particles of the active coating material have a particle size in the range of from 1 to 45 microns.

131. A method according to claim 120, wherein 90% by weight of the particles have a size less than 70 microns, 50% by weight have a size less than 40 microns and 10% by weight have a size less than 10 microns.

132. A method according to claim 120, wherein the quantity of active material in the active coating applied to the substrate is substantially equal to one dose of the active material.

133. A method according to claim 120, wherein the wafer removed from the coated substrate is a solid dosage form.

134. A method according to claim 120, wherein the active coating material is applied to a plurality of individual regions on the surface of the substrate.

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135. A method of coating a substrate, the method comprising the steps of applying an active coating material to the substrate to form an active coating layer, the active coating material comprising biologically active material, wherein the active coating layer is removable from the substrate, and the active coating material is applied electrostatically as a powder, and wherein after the active coating layer is applied the active coating material is fused to form an active film coating on the surface of the substrate, and wherein the active material is applied to a surface of the coating apparatus and the active coating is removed as a wafer.

136. A method according to claim 135, wherein the active material is

applied to a conveyor belt.

137. A method according to claim 135, which further includes the step of applying a cover coating material onto the active coating layer to form a cover coating layer such that the active coating layer is substantially completely covered by the cover coating layer, and such that that cover coating layer is removable from the substrate, and wherein the cover coating material is applied electrostatically as a powder and after application is fused to form a cover film coating.

138. A method according to claim 137, wherein the method includes the step of applying a second active coating layer onto a surface of the substrate, the second active coating layer forming a second active coating region on the surface of the substrate, the second active coating layer being removable from the substrate, and applying a second cover coating layer onto the second active coating layer to form a second cover coating layer such that the second active coating layer is substantially completely covered by the second cover coating layer, the second cover coating layer being substantially separate from the first cover coating layer, and being removable from the substrate.

139. A method according to claim 135, which comprises applying to the substrate a base coating layer, applying the active material to the base layer and

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applying a cover coating layer over the active coating layer, the three layers being removable together by peeling from the substrate in the form of a three-layer wafer.

140. A method according to claim 139, wherein the base coating layer and the cover coating layer are each applied as a powder and each fused to form a film.

141. A method according to claim 135, wherein at least 90% by weight of the particles of the active coating material have a particle size in the range of from 1 to 45 microns.

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142. A method according to claim 135, wherein 90% by weight of the particles have a size less than 70 microns, 50% by weight have a size less than 40 microns and 10% by weight have a size less than 10 microns.

143. A method according to claim 135, wherein the quantity of active material in the active coating applied to the substrate is substantially equal to one dose of the active material.

144. A method according to claim 135, wherein the wafer removed from the coated substrate is a solid dosage form.

Sub C5 145. A method according to claim 135 wherein the active coating material is applied to a plurality of individual regions on the surface of the substrate.

146. A method of coating a plurality of coating regions onto the surface of a substrate, the method comprising the steps of:

(a) applying an active coating material to a surface of the substrate to form a plurality of active coating regions on the surface comprising active coating layers, the active coating material comprising biologically active material, and

(b) applying cover coating material to a surface of the substrate to form a plurality of cover coating regions, the cover coating regions forming layers of cover coating material, each active coating region being substantially completely covered by a cover coating region, such that each region of active coating and cover coating is removable from the surface of the substrate.

147. A method according to claim 146, the method including the step of removing the active coating regions from the substrate to form wafers comprising active material.

Sub C5 148. A method of coating a plurality of coating regions onto the surface of

a substrate, the method comprising the steps of:

(a) applying an active coating material to a surface of the substrate to form a plurality of active coating regions on the surface comprising active coating layers, the active coating material comprising biologically active material and being applied electrostatically as a powder,

(b) applying a cover coating material to a surface of the substrate to form a plurality of cover coating regions, the cover coating regions forming layers of cover coating material, each active coating region being substantially completely covered by a cover coating region, such that each region of active coating and cover coating is removable from the surface of the substrate.

149. A method according to claim 148, wherein after the active coating material is applied the active coating material is fused to form regions of active film coating on the surface of the substrate.

150. A method according to claim 148, wherein the cover coating material is applied electrostatically as a powder and after application is fused to form regions of cover film coating.

151. A method according to claim 148, the method including the step of

removing the active coating regions from the substrate to form wafers comprising active material.

152. A method according to claim 148, wherein at least 90% by weight of the particles of the active coating material have a particle size in the range of from 1 to 45 microns.

153. A method according to claim 148, wherein 90% by weight of the particles have a size less than 70 microns, 50% by weight have a size less than 40 microns and 10% by weight have a size less than 10 microns.

154. A method of coating a plurality of coating regions onto the surface of a substrate, the method comprising the steps of:

(a) applying an active coating material to a surface of the substrate to form a plurality of active coating regions on the surface comprising active coating layers, the active coating material comprising biologically active material

(b) applying a cover coating material to a surface of the substrate to form a plurality of cover coating regions, the cover coating regions forming layers of cover coating material, each active coating region being substantially completely covered by a cover coating region, such that each region of active coating and

cover coating is removable from the surface of the substrate, and wherein the active material is applied to a surface of the coating apparatus and the active coating regions are removed as wafers.

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155. A method according to claim 154, wherein the active material is applied to a conveyor belt.

156. A method of coating a plurality of coating regions onto the surface of a substrate, the method comprising the steps of:

(a) applying an active coating material to a surface of the substrate to form a plurality of active coating regions on the surface comprising active coating layers, the active coating material comprising biologically active material and being applied electrostatically as a powder,

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(b) applying a cover coating material to a surface of the substrate to form a plurality of cover coating regions, the cover coating regions forming layers of

cover coating material, each active coating region being substantially completely covered by a cover coating region, such that each region of active coating and cover coating is removable from the surface of the substrate, and wherein the active material is applied to a surface of the coating apparatus and the active coating regions are removed as wafers.

157. A method according to claim 156, wherein after the active coating material is applied the active coating material is fused to form regions of active film coating on the surface of the substrate.

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158. A method according to claim 156, wherein the cover coating material is applied electrostatically as a powder and after application is fused to form regions of cover film coating.

159. A method according to claim 156, wherein the active material is applied to a conveyor belt.

Jul 13
160. A method according to claim 156, wherein at least 90% by weight of the particles of the active coating material have a particle size in the range of from 1 to 45 microns.

161. A method according to claim 156, wherein 90% by weight of the particles have a size less than 70 microns, 50% by weight have a size less than 40 microns and 10% by weight have a size less than 10 microns.

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162. A method of coating a substrate, the method comprising the steps of applying an active coating material to the substrate to form an active coating

layer, the active coating material comprising biologically active material, wherein the active coating layer is removable from the substrate, and the active coating material is applied electrostatically as a powder, and wherein the active coating layer is removed from the substrate as a wafer and divided into smaller portions.

163. A method according to claim 162, wherein after the active coating layer is applied the active coating material is fused to form an active film coating on the surface of the substrate.

164. A method according to claim 162, wherein active coating material is applied to a plurality of individual regions on the surface of the substrate.

165. A method according to claim 164, wherein the amount of active coating material deposited on a given area of the substrate is controlled such that the product can subsequently be divided into portions with each portion containing a pre-determined amount of active coating material, each pre-determined amount being one dose of the active material.

166. A method of coating a substrate, the method including the steps of applying an active coating material to the substrate to form an active coating layer, the active coating material comprising biologically active material, wherein the active coating layer is removable from the substrate, and wherein the active

material is applied to a surface of the coating apparatus and the active coating is removed as a wafer and divided into smaller portions.

167. A method of coating a substrate, the method comprising the steps of applying an active coating material to the substrate to form an active coating layer, the active coating material comprising biologically active material, wherein the active coating layer is removable from the substrate, and the active coating material is applied electrostatically as a powder, and wherein the active material is applied to a surface of the coating apparatus and the active coating is removed as a wafer and divided into smaller portions.

168. A method according to claim 167, wherein after the active coating layer is applied the active coating material is fused to form an active film coating on the surface of the substrate.

169. A method of coating a substrate, the method comprising the steps of applying an active coating material to the substrate to form an active coating layer, the active coating material comprising biologically active material, wherein the active coating layer is removable from the substrate, and the active coating material is applied electrostatically as a powder, and wherein active coating material is applied to a plurality of individual regions on the surface of the substrate, and wherein the amount of active coating material deposited on a

given area of the substrate is controlled such that the product can subsequently be divided into portions with each portion containing a predetermined amount of active coating material, each predetermined amount being one dose of the active material.

Sub C1 170. A method according to claim 169, wherein after the active coating layer is applied the active coating material is fused to form an active film coating on the surface of the substrate.

Sub C1 171. A coated substrate comprising an active coating layer that has been applied electrostatically as a powder on a surface of the substrate, the active coating layer including biologically active material and in which the active coating layer is removable from the surface of the coated substrate.

Sub C8 172. A coated substrate according to claim 171, wherein the active coating layer is a fused film layer.

173. A coated substrate according to claim 171, the substrate further including a cover coating layer on a surface of the substrate, the cover coating layer substantially completely covering the active coating layer wherein the cover coating layer is removable from the substrate together with the active coating layer or separately.

174. A coated substrate according to claim 173, wherein the cover coating layer is a fused film layer which has been applied electrostatically as a powder and fused.

175. A coated substrate according to claim 173, wherein the cover coating layer includes biologically active material.

176. A coated substrate according to claim 171, wherein the quantity of biologically active material on the substrate is substantially equal to one dose of the biologically active material.

177. A coated substrate according to claim 171, wherein the active coating layer removed from the substrate constitutes a solid dosage form.

178. A coated substrate according to claim 171, wherein the active coating layer comprises

- i) a continuous phase component
- ii) the biologically active material
- iii) a charge-modifying component and
- iv) a flow aid.

179 179. An intermediate product for use in producing a plurality of solid dosage forms, the intermediate product comprising a substrate and active coating comprising biologically active material that has been applied electrostatically as a powder in a plurality of regions on the substrate, each region of active coating being removable from the surface of the substrate.

180 180. An intermediate product according to claim 179, wherein the active coating is fused.

181. An intermediate product for use in producing a plurality of solid dosage forms, the intermediate product comprising a substrate and active coating comprising biologically active material in a plurality of regions on the substrate, the active coating regions being removable from the surface of the substrate, wherein each active coating region includes a cover coating region comprising a layer of cover coating material, each active coating region being substantially completely covered by a cover coating region and such that each region of active coating and cover coating is removable from the surface of the substrate.

182. An intermediate product according to claim 181, wherein the active coating layer has been applied electrostatically as a powder.

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183. An intermediate product according to claim 181, wherein the active coating layer comprises i) a continuous phase component
ii) the biologically active material iii) a charge-modifying component
and
iv) a flow aid.

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184. An intermediate product for use in producing a plurality of solid dosage forms, the intermediate product comprising a substrate and active coating material comprising biologically active material that has been deposited electrostatically as a powder on the substrate, the amount of active coating material deposited on a given area of the substrate being such that the product can subsequently be divided into portions with each portion containing a predetermined amount of active coating material, each predetermined amount being one dose of the active material, and the active coating layer being removable from the surface of the substrate.

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C11

185. An intermediate product according to claim 184, wherein the active coating material is fused.

186. An intermediate product according to claim 184, which is a three-layer wafer comprising an active material layer sandwiched between two non-active layers.--

add C12